

**MDS (MATERIAL DATA SHEETS)**

Product name			Photocoupler	
Business Dealing name			PC817X2NSZ2B PC817X3NSZ2B PC817X1NSZ2B	
Item	Material	CAS No.	Wt of Item (mg)	Wt. of material (mg)
Infrared Light Emitting Diode	GaAs	1303-00-0	0.030	0.030
Phototransistor	Si	7440-21-3	0.148	0.148
Leadframe	Cu	7440-50-8	63.297	61.319
	Zn	7440-66-6		0.094
	Fe	7439-89-6		1.330
	P	7723-14-0		0.014
	Ag (plating)	7440-22-4		0.242
	Cu (plating)	7440-50-8		0.297
Bonding Wire	Au	7440-57-5	0.027	0.027
Transparent Compound	Silicone Resin	-	1.000	1.000
Semitransparent Compound	Fused Silica	60676-86-0	39.966	27.576
	Silica, Crystalline	14808-60-7		0.400
	Epoxy Resin	-		7.993
	Phenolic Resin	9003-5-4		3.997
Opaque Compound	Silica	7631-86-9	122.133	75.722
	Epoxy Resin	-		36.640
	Phenolic Resin	-		9.160
	Carbon Black	1333-86-4		0.611
Terminal Plating	Sn	7440-31-5	3.354	3.354
Silver Epoxy Resin	Ag	7440-22-4	0.046	0.034
	DIGLYCIDYLETHER OF B.P.A	25068-38-6		0.002
	Epoxy Resin	25068-38-6		0.010
			Total (mg)	230.000

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Responsible Person: Yoshihisa Takahashi  
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